Department of Mechanical Engineering

CIE-I

Date	22 nd October 2024	Maximum Marks	50
Course Code	ME242AT	Duration	90 Min
Course Name	Material Science for Engineers	USN:	

Q. No.	Questions	M.	BT	CO
1	How many electrons can occupy a P orbital?	1	1	1
2	The principal quantum number (n) refers to the and of the orbital.	1	. 1	1
3	In which type of bond do atoms share electrons?	1	1	1
4	A large energy gap between valence and conduction bands is the characteristic of which type of materials	.1	. 1	1
5	What is the basic repeating unit in a crystal lattice?	1	1	1
6	Single atom or ion missing or occupying an irregular position is type of defect in a crystal structure	1	1	1
7	The fractional increase in the length per unit rise in temperature in solids is known as	1	1	2
8	Identify the thermoelectric effect in which the temperature difference between two different materials or junctions in a circuit leads to the generation of an electric voltage	1	2	2
9	Define dielectric strength.	. 2	1	2
	PART B			
1	a) Describe Pauli Exclusion Principle and Aufbau principle.	05	2	1
	b) With the help of neat sketches explain the Secondary bonds with examples.	05	2	1
2	Classify solid materials based on the band gaps. Explain them briefly giving examples	10	2	1
3	a) Calculate Atomic packing factor for HCP unit cell.	05	3	1
	b) Differentiate Edge dislocation and Screw dislocation			
4	Explain the properties and applications of metals and ceramics. Give two examples each. a) Illustrate the temperature gradient along a second.	05	2	
	a) Illustrate the temperature gradient along a conductor resulting in the absorption or release of heat in Thomson thermoelectric effect using appropriate electric.	10	3	1
5.	ability appropriate sketches.	05	3	2
	b) Write a note on Insulating materials highlighting their applications	05	2	

BT-Blooms Taxonomy, CO-Course Outcom

Marks	Part	ticulars	COI	CO2	1000		utcome	s, M-Ma	rks			
Distribution		Marks	46	14	-	CO4	L1	L2	L3	L4	1.5	16
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Department of Mechanical Engineering

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C	1	D	-	1	1

Date	3 rd December 2024	Maximum Marks	50+10
Course Code	ME232TB	Duration	120 Min
Course Name	Material Science for Engineers	USN:	

Part A (Quiz)

Sl. No.	Questions	M	BT	CO
1.	Semiconductor device with a p-n junction which produces current by absorption of light in the depletion region is termed as	1	L1	2
2.	is the metal joining process in which parent metal pieces are heated either to plastic or molten state.	1 ,	L1	2
3.	If the emission of radiation occurs longer than 10 ⁻⁸ seconds is known as	1	L1	2
-4.	Alloying elements of HSS are	1	L1	2
5.	Lightest of commonly used metals is	1	L1	2
6.	Define young's modulus of a material with equation.	2	L2	2
- 7.	is the type of glass that cannot allow heat through it because of air between the layers and acts as good insulators.	1	L1	2
8.	Concrete is a composite material made up at and	2	L1	2

Part-B (Test)

l. No.	Questions	M	Dar	100
1 a)	What is piezoelectric effect? Explain the applications of piezoelectric materials.	05	BT L2	2
b)	Distinguish between ductile and brittle fracture.	05	L2	2
2	With the stress strain diagram explain the mechanical properties of a ductile metal.	10	L2	2
3 a)	Discuss the applications of semiconductors.	05	L3	2
b)	Explain four different types of cast iron based on microstructure, properties and applications.	05	L2	2
4 a)	With a neat sketch describe the steps to be followed in metal casting process.	05	L2	2
b)	Compare thermoplastics with thermosetting plastics.		LIZ	2
5 a)	Justify the need for composite materials. Classify composite materials.	05	L3	2
b)	What is a biomaterial? List the List th	05	L3	2
	What is a biomaterial? List the desirable properties of biomaterials.	05	1.2	2

RV COLLEGE OF ENGINEERING®

(An Autonomous Institution Affiliated to VTU)

III Semester B. E. Regular / Supplementary Examinations Jan / Feb-2025

Common to All Programs

MATERIAL SCIENCE FOR ENGINEERS
Time: 03 Hours

Instructions to candidates:

Maximum Marks: 100

1. Answer all questions from Part A. Part A questions should be answered in first three pages of the answer book only.

2. Answer FIVE full questions from Part B. In Part B question number 2 is compulsory. Answer any one full question from 3 and 4, 5 and 6, 7 and 8, 9 and 10.

	PART-A	M	BT	co
	Atomic Decline Factor (ADE) in	01	1	1
1 1	1 0 000			
1	packed structure is	01	1	1
1.3				
	and	02	1	1
* 1.	is the vacancy in a crystal structure.	01	1	1
1.	True stress is	01	1	1
1.		00	1	1
	be classified as and	02	1	2
- 1.		01	1	1
1.		01	1	1
• 1.		01	1	1
• 1.		02	1	1
1.	can be and Heat treatment processes can be broadly classified as &	02	1	1
1.	Heat treatment processes can be stodary excessive as a	02	1	1
1	Two types of surface hardening are &	02	i	1
THE RESERVE OF THE PARTY OF THE	13 Ball milling is used for	01	1	1
1 . 1.		01	1	1
• 1.		01	1	1

PART-B

a	List and explain different crystal imperfections.	08	1	1
b	Define the following:-			
	iv) Unit cell	08	1	1
		CAPPARA CONTRACTOR OF THE PARA		
a	With the help of stress strain diagram explain plastic properties			
	of a material.	08	2	2
b	Define dielectric constant. Give the detailed description for			-
	dielectric behavior of a material.	08	1	2
	OR			-
a				
	1 ii) Pettier ellect	08	1	
	a b	b Define the following:- i) Space Lattice ii) Co-ordination Number. iii) Atomic packing factor iv) Unit cell With the help of stress strain diagram explain plastic properties of a material. b Define dielectric constant. Give the detailed description for dielectric behavior of a material. OR	b Define the following:- i) Space Lattice ii) Co-ordination Number. iii) Atomic packing factor iv) Unit cell a With the help of stress strain diagram explain plastic properties of a material. b Define dielectric constant. Give the detailed description for dielectric behavior of a material. OR With appropriate sketches, explain the following: i) Seebeck effect	b Define the following: i) Space Lattice ii) Co-ordination Number. iii) Atomic packing factor iv) Unit cell a With the help of stress strain diagram explain plastic properties of a material. b Define dielectric constant. Give the detailed description for dielectric behavior of a material. OR With appropriate sketches, explain the following: i) Seebeck effect ii) Peltier effect